

SID

Factory: Rot am See

Article:

566

ML8

Provided:

Landwehr, Melanie

Customer:

Date:

15.12.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	306		2
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		3
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		4
C-RS-FR4-ML-0.51mm-070+070-TG150-HF	50200736	70	L2	5
		510		
		70	L3	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	272		6
		0		7
		0		8
C-RS-FR4-ML-0.51mm-070+070-TG150-HF	50200736	70	L4	9
		510		
		70	L5	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	272		10
		0		11
		0		12
C-RS-FR4-ML-0.51mm-070+070-TG150-HF	50200736	70	L6	13
		510		
		70	L7	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	309		14
		0		15
		0		16
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	17

Thickness after Pressing

B00:

3090 µm

Tol+:

320 µm

Tol-:

320 µm

Dmax:

3410 µm

Dmin:

2770 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

3200 µm

Tol+:

320 µm

Tol-:

320 µm

Dmax:

3520 µm

Dmin:

2880 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

3145 µm

Version 1.2.14.15

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